

NOTES:

1.MATERIAL:

HOUSING: THERMOPLASTIC WITH GLASS FIBER.HALOGEN FREE. UL94V-0.

LATCHS: THERMOPLASTIC WITHOUT GLASS FIBER.HALOGEN FREE, UL94V-0.

CONTACTS: COPPER ALLOY

2. PLATING SPECIFICATION:

2-50u" Ni UNDERPLATE

100u" TIN TAIL AREA

GOLD FLASH CONTACT AREA

CONTACTS AREA: GOLD OVER NICKEL

SOLDER TAIL AREA: MATTE TIN OVER NICKEL

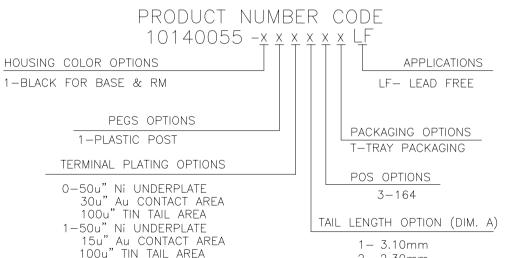
3. WARNING: THE MAXIMUM ALLOWABLE ANGLE TO WITHDRAWAL THE DAUGHTER CARD FROM RETAINER BY 25 DEGREE.

4. PRODUCT SPECIFICATION: GS-12-233. PACKAGING SPECIFICATION: GS-14-992.

5. NO TIE BAR PERMITTED FOR CARD EDGE TO LEADING EDGE OF PAD FOR PINS "A1" AND "B81."

2 - 2.30 mm

- 6. CHAMFER EDGE MUST BE FREE OF CUTTING BURRS.
- 7. THIS PRODUCT MEETS EUROPEN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004.
- 8. ALL HOLE DIAMETERS ARE FINISHED HOLE SIZES.
- 9. THE HOUSING WILL WITHSTAND EXPOSURE TO 260C° PEAK TEMPERATURE FOR 5 SECONDS IN WAVE SOLDER APPLICATION WITH 1.46MM MINIMUM THICK CIRCUIT BOARD .



mat'l. code Isurface /tolerance projection product family ASME Y14.5 tolerances unless otherwise specified title |ltr|ecn no|dr|date .0±.0.30 MM angles .00±.0.20 .000±.0.10 scale N/A ZHENHUA_LIU 2016-09-18 dwg no ZHENHUA_LIU 2016-09-18 lengd **Amphenol**

STONE_LI

PM_ZHENG

2016-09-18

2016-09-18

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PCI_EXPRESS_CARD_EDGE_GEN3 INTEGRATE-TYPE_ASS'Y sheet 4 of 4 size

10140055 CUSTOMER Drawing type

PCI_EXPRESS

form: A4mmXLc-2016-02-24

revision B sheet

PDS: Rev :B

STATUS:Released Printed: Nov 04, 2016

appd

В

sheet